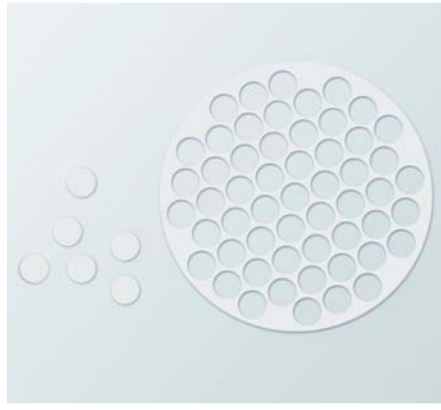
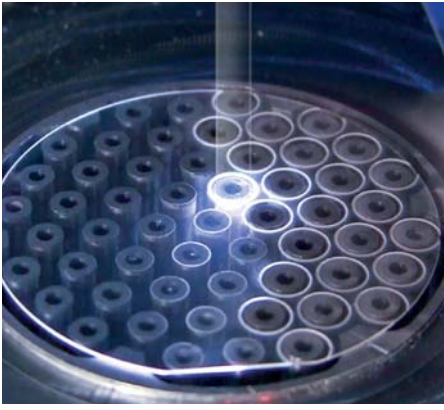


ELC 420
LASER PLATFORMS FOR ELECTRONICS



ELC 420

Laser Platforms for Electronics



TECHNICAL SPECIFICATIONS

ELC 420

Dimensions (L x W x H)	2,900 mm x 2,800 mm x 2,700 mm
Weight	5,000 - 5,500 kg
Power supply	200 - 480 V
Compressed dry air	6 - 7 bar
Cooling Water	5 - 20 l/min
Working area	2 x 2 chucks Scan field 55 mm x 55 mm
Accuracy	< ±20 µm absolute < ±10 µm repeatability
Laser sources	Several laser sources
Laser spot size	10 - 300 µm
Beam delivery	Scanner
Safety	CE

PROCESS AND SYSTEM VALUES

Material	plane sapphire (different crystal orientations)
Material thicknesses	< 650 µm
Sidewall roughness values	~ 0,8 µm
Ablation rate	25 mm ³ /min (parallel operation of 2 scanner)
Generation of chamfer possible	

PROCESS AND SYSTEM LIMITATIONS

Occurrence of side wall taper angle (~ 10°)	
For basic trials only mechanical aligners possible	
Distance between neighboring structures > 750 µm	

FEATURES

- Universal cutting system
- Scanner setup
- Highly modular system design
- Fast manufacturing
- High volumes and quick ramp-up
- Highly accurate system
- Standalone and line integrable system
- 4 x Scanner heads
- Highly effective exhaust system

OPTIONAL

- Several laser sources available
- Fully automatic handling (mass production)
- Semi-automatic handling (R&D)
- MES interface
- Integrated process metrology
- Import of CAD files (e.g. DXF, DWG)
- Vision system
- 1 x or 2 x Scanner heads